



<b>[FC1] Plasma &amp; Atomic Layer Etching I</b>	
<b>Date / Time</b>	July 27 (Fri.), 2018 / 09:10-10:40
<b>Place</b>	Room C (#114)
<b>Session Chair(s)</b>	Eric A Joseph (IBM Thomas J. Watson Research Center, USA) Fred Roozeboom (Eindhoven Univ. of Tech., Netherlands)

**FC1-1 [Keynote]**

**09:10-09:50**

Challenges to the Next Generation Semiconductor Equipment by Using Plasma

Kuntack Lee

*Samsung Electronics Co., Ltd., Korea*

**FC1-2**

**09:50-10:10**

Plasma-Assisted Atomic Layer Etching of Si-Based Dielectric Films Studied Using in Situ Surface Diagnostics

Sumit Agarwal<sup>1</sup>, Ryan J. Gasvoda<sup>1</sup>, Scott Wang<sup>2</sup>, Ranadeep Bhowmick<sup>2</sup>, and Eric A. Hudson<sup>2</sup>

<sup>1</sup>Colorado School of Mines, USA, <sup>2</sup>Lam Research Corporation, USA.

**FC1-3 [Invited]**

**10:10-10:40**

Frontiers of Industrial Application of Atomic Layer Etching

Alok Ranjan<sup>1</sup> and Peter Ventzek<sup>2</sup>

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